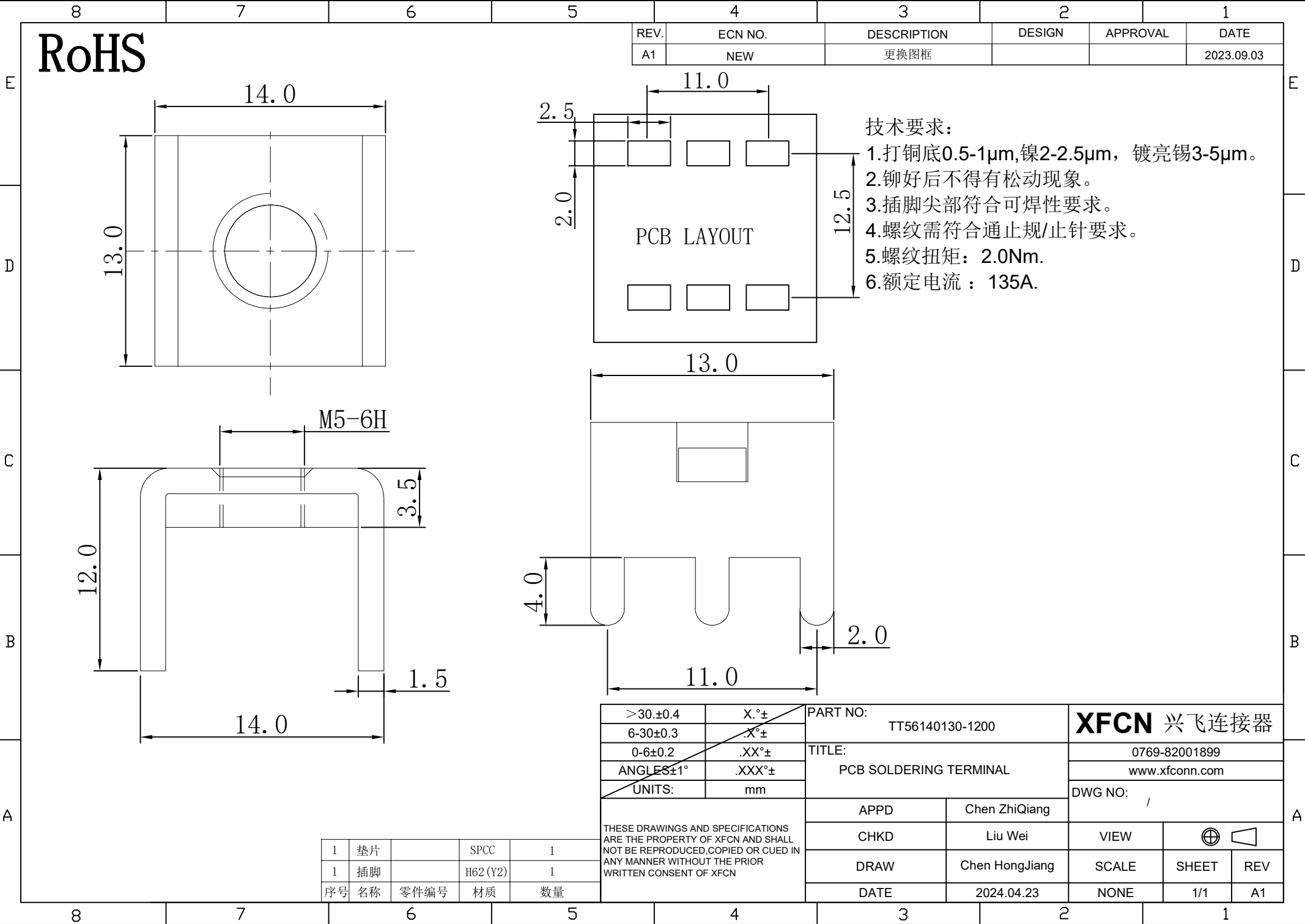




RoHS

REV.	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.09.03

PCB LAYOUT

- 技术要求:
- 1.打铜底0.5-1μm,镍2-2.5μm, 镀亮锡3-5μm。
 - 2.铆好后不得有松动现象。
 - 3.插脚尖部符合可焊性要求。
 - 4.螺纹需符合通止规/止针要求。
 - 5.螺纹扭矩: 2.0Nm.
 - 6.额定电流 : 135A.

1	垫片		SPCC	1
1	插脚		H62 (Y2)	1
序号	名称	零件编号	材质	数量

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PART NO: TT56140130-1200		XFCN 兴飞连接器		
TITLE: PCB SOLDERING TERMINAL		0769-82001899		
		www.xfconn.com		
		DWG NO: /		
APPD	Chen ZhiQiang	VIEW	⊕	
CHKD	Liu Wei	SCALE	SHEET	REV
DRAW	Chen HongJiang			
DATE	2024.04.23	NONE	1/1	A1